



MLB:sa 3009-3751 10/13/92

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Art Unit 3102

Richard S. Ketcham

Serial No. 07/628,440

Filed: December 14, 1990

For: OPTIMIZED PIEZOELECTRIC
RESONATOR-BASED NETWORKS
AND ASSOCIATED METHOD

Date: October 13, 1992

Examiner: M. Budd

CERTIFICATE OF MAILING

I HEREBY CERTIFY THAT THIS PAPER AND THE DOCUMENTS REFERRED TO AS BEING ATTACHED OR ENCLOSED HERewith ARE BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE ON October 13, 1992 AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: BOX NON-FEE AMENDMENT, COMMISSIONER OF PATENTS AND TRADEMARKS, WASHINGTON, D.C. 20231.


Mark L. Becker
Attorney for Applicant

RECEIVED

OCT 23 1992

GROUP 210

AMENDMENT

TO THE COMMISSIONER
OF PATENTS AND TRADEMARKS:

In response to the Office action dated July 13, 1992, please amend the above-identified patent application as follows:

In the Specification:

Page 1, lines 9 and 10, delete "without the need for additional interconnects to complete connections", replace with

B1
--with interconnects on one or either principal face of a piezoelectric plate or membrane--.

Page 1, line 23, after "wafer" add --plates, or films--.

B2
Page 1, line 24, delete "Through" and replace with --These thin structures may be formed by thin film deposition onto a suitable substrate which leaves one principal surface of the material relatively inaccessible for interconnects. Resonators may be fabricated from these thin films and through--.

B3
Page 2, line 26, at end add --The situation is further complicated by the desirability of production testing as many as 600 piezoelectric resonator networks on each 4-inch-diameter wafer substrate prior to final assembly. Microwave probe testing